L	Hits	Search Text	DB	Time stamp
Number				
1	1	ID adj marking and wafer and circuit	USPAT;	2004/09/16
			EPO; JPO;	18:52
			DERWENT	
2	978	identi\$6 and circuit and marking and	USPAT;	2004/09/16
1		wafer	EPO; JPO;	18:53
	ļ		DERWENT	
3	47143	laser adj beam and plate	USPAT;	2004/09/16
			EPO; JPO;	18:54
		•	DERWENT	
4	105	(identi\$6 and circuit and marking and	USPAT;	2004/09/16
		wafer ) and (laser adj beam and plate)	EPO; JPO;	18:54
		-	DERWENT	